CUI DEVICES

MODEL: HSS-B20-0508H-01 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- solder pins for secure PCB mounting
- black anodized finish

RoHS

MODEL

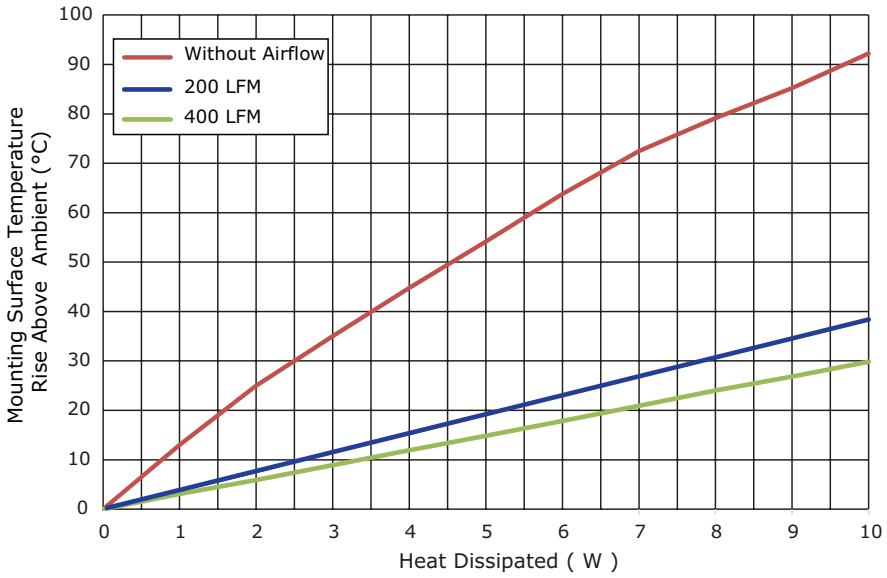
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSS-B20-0508H-01	10.14	12.99	3.51	3.10	7.40

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	12.99	3.51	3.10
2	24.98	7.29	5.90
3	35.01	11.39	8.91
4	44.78	15.00	11.93
5	54.16	18.87	14.84
6	63.78	22.93	17.86
7	72.49	26.77	20.92
8	79.12	30.54	24.03
9	85.23	34.46	26.83
10	92.25	38.38	29.87

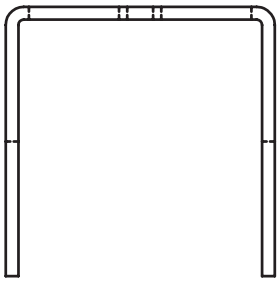
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature

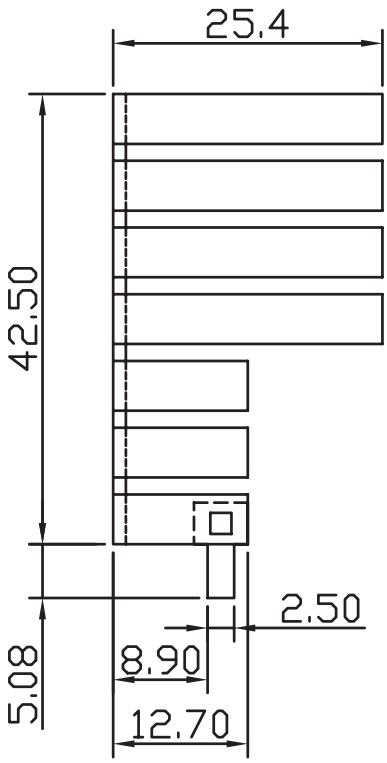


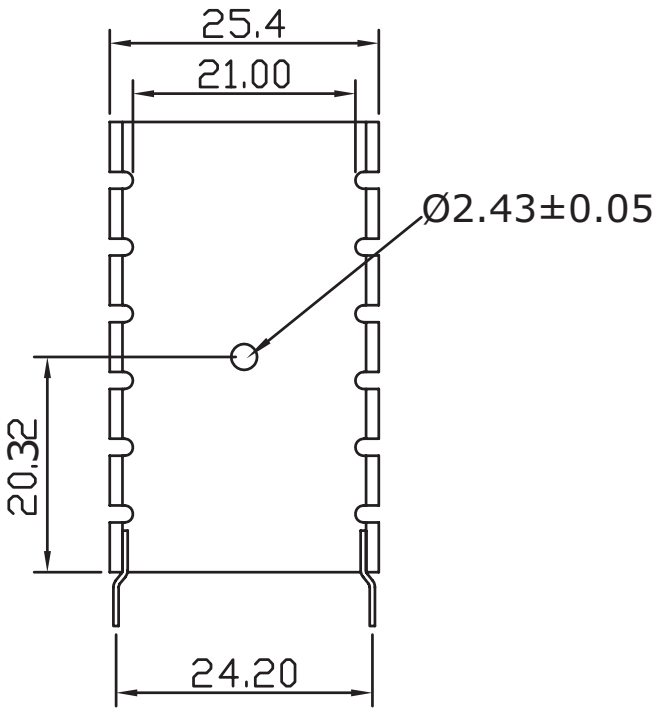
MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL1100
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	7.8 g







REVISION HISTORY

rev.	description	date
1.0	initial release	04/03/2017
1.01	brand update	02/12/2020

The revision history provided is for informational purposes only and is believed to be accurate.